POLYTRONICS
POLYTRONICS TECHNOLOGY CORP.

PRODUCT
DATASHEET

SMFD1206 Series Surface Mount Fuses Devices

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Description

Polytronics SMFD1206 series surface mount slow-blow fuse utilizes thick film process with extremely stable fusing element. The glass over coating can tolerate higher temperature profile, and the non-flammable ceramic substrate offers better heat conductivity and safety. SMFD1206 series is also RoHS compliant and halogen-free to meet global environmental standard.

Features

- Slow-blow
- Compact size
- Thick film manufacturing method
- Ceramic substrate with silver fusing element
- Excellent environmental integrity

Application

- Battery pack
- Digital camera
- Game equipment
- Wireless base station
- LCD monitors and modules
- PC related equipment / peripherals
- Power supply
- Medical device

Agency Approval and Environmental Compliance

Agency	File Number
c UL us	UL/CSA:E331807
TÜV	TÜV: J50583170

Regulation	Standard
RoHS	2011/65/EU
Halogen Free	IEC 61249-2-21:2003

Electrical Characteristics

Part Number	Marking	Current Rating (A)	Voltage Rating	Interrupting Rating	Typical Cold DCR† (Ω)	Typical I²T‡ (A²S)	Agency Approval	
							c UL us	
SMFD1206P050	F	0.5	75V	UL: 50A@75V DC 50A@75V AC TÜV 50A@63V DC 50A@63V AC	1.000	0.0052	✓	-
SMFD1206P075	G	0.75			0.640	0.0615	✓	-
SMFD1206P100	H	1.0			0.320	0.245	✓	✓
SMFD1206P150	K	1.5			0.140	0.294	✓	✓
SMFD1206P200	N	2.0			0.092	0.788	✓	✓
SMFD1206P250	O	2.5			0.065	1.149	✓	✓
SMFD1206P300	P	3.0			0.036	2.300	✓	✓
SMFD1206P350	R	3.5			0.030	2.563	✓	✓
SMFD1206P400	S	4.0			0.023	3.667	✓	✓
SMFD1206P500	T	5.0			0.016	4.260	✓	✓
SMFD1206P600	6	6.0			0.0125	9.848	✓	✓
SMFD1206P700	U	7.00			0.007	11.176	✓	✓

† Measured at ≤ 10% rated current and 25°C
‡ Melting I²T at 10 times of rated current

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Electrical Specification

Ampere Rating	% of Current Rating	Opening Time
0.5A~7A	100%	4 Hours Min.
1.0A~7A	200%	60 Seconds Max.
0.5A	250%	60 Seconds Max.
0.75A	250%	20 Seconds Max.
0.5A~0.75A	1000%	0.1 mSec. Min
1.0A~7A	1000%	1.0 mSec. Min

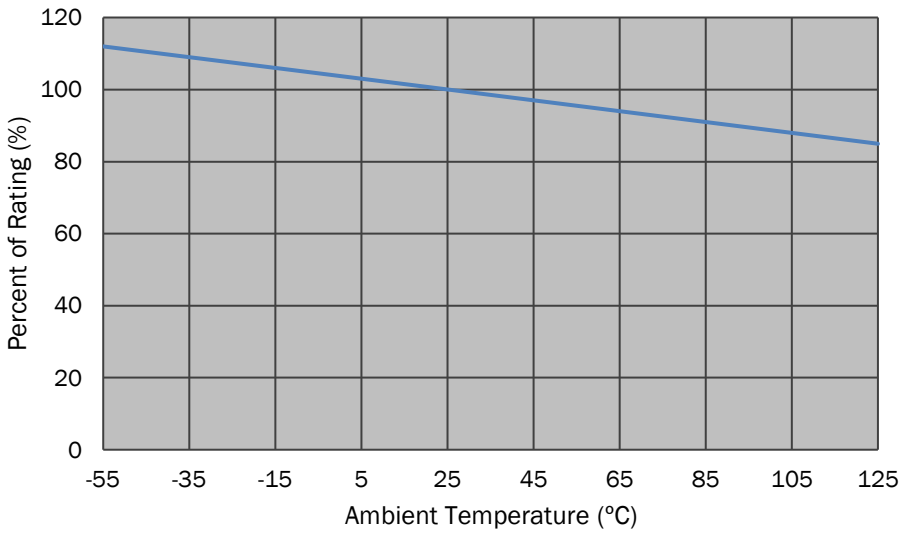
Physical Specifications

Materials	Substrate: Ceramic Terminations: Silver over-plated with 100% tin Element: Silver or Silver/palladium
Solderability	MIL-STD-202
Soldering Parameters	Wave Solder: 260°C, 10 seconds max. Reflow Solder: 260°C, 20 seconds max. Hand Solder: 350°C, 5 seconds max.

Environmental Specifications

Operating Temperature	-55°C to 125°C

Thermal Derating Curve



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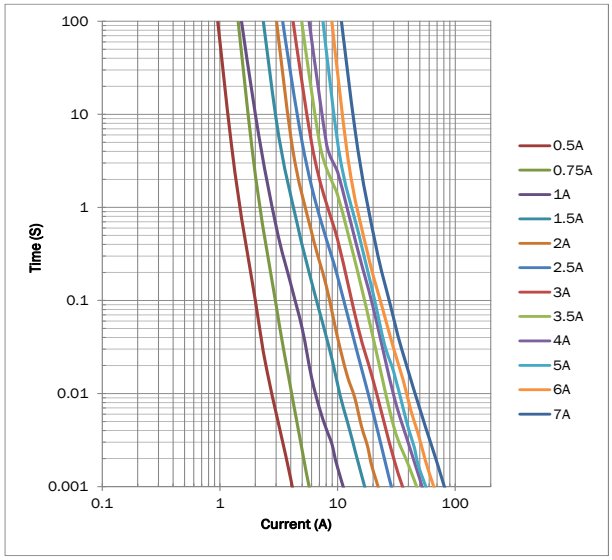
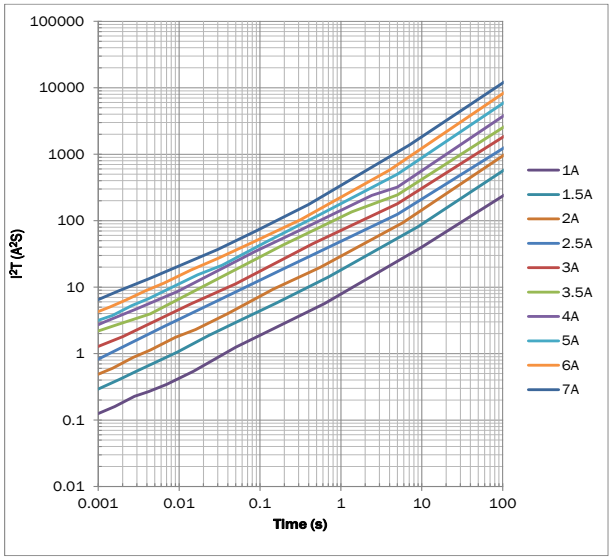
Time-Current Curve



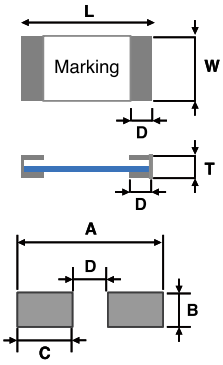
I²T vs Time Curve



Physical Dimensions (mm.)

Dimensions (mm)

L	W	T	D
3.10±0.20	1.55±0.20	0.55±0.20	0.35±0.20



Recommended Solder Pad Dimension (mm)

A	B	C	D
4.4±0.5	2.4±0.3	1.2±0.3	2.0±0.3

Dimensions of Standard Test Board (mm)

Ampere Rating	Board Thickness	Copper Layer Thickness	Copper Trace Width
0.5A~6A	1.6	0.035	5.0
7A	1.6	0.070	7.5

Part Number System

SMF D 1206 P □□□

- Current Rating in 100X Ampere
- Polytronics Symbol
- Device Dimension in 1/100 inch
- Series, D=Slow-blow 63V
- Surface-Mount Fuse

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Reliability Test

Characteristics	Test condition / Methods	Requirement	Test Reference
Voltage Drop	100% In	Deviation between the mean value: <15%	IEC 60127-4
Time/Current	100% In	No fusing, 4 hours min.	UL248-14
	200% In	1.0A~7.0A ≤ 60sec	Refer to Spec.
	250% In	0.5A ≤ 60sec 0.75A ≤ 20sec	Refer to Spec.
	1000% In	0.5A~0.75A: > 0.1 ms 1.0A~7.0A: > 1.0 ms	IEC60127-4
Endurance Test	100% In, 1hour on, 15min off, 100cycles; followed by 1hour at 125% In	|ΔR|<10%	IEC60127-4
Temperature Rise	100% In	|ΔT |<75°C	IEC60127-4
Interrupting Ability	UL: 50A/75V DC, 50A/75V AC TÜV: 50A/63V DC, 50A/63V AC	Without permanent arcing, ignition, and bursting of fuse link	UL 248-14 IEC60127-4
Solderability	240°C ± 5°C, 3sec ± 0.5sec	95% coverage min	IEC 60127-4 MIL-STD-202 Method 208
Resistance to Soldering	260°C ± 5°C, 10sec ± 0.5sec	|ΔR|: <10% Legible appearance	MIL-STD-202 Method 210
Bending Test	Distance between holding points: 90mm Bending: 1 mm; Time: 10 sec	|ΔR|: <10% No mechanical damages	IEC 60127-4
High Temperature Operating Life	70°C ± 2°C at 60% In for 96 hours	|ΔR|: <10%; no fusing	MIL-STD-202 Method 108
Low Temperature Storage	-55°C ± 3°C for 96 hours	|ΔR|: <10%	IEC60068-2-1
High temperature Storage	125°C ± 2°C for 96 hours	|ΔR|: <10%	IEC60068-2-2
Humidity (Steady State)	40°C ± 2°C, 90~95%RH for 1000 hours	|ΔR|: <10%	MIL-STD-202 Method 103
Salt Spray	5% salt solution, 48 hours exposure	|ΔR|: <10% Legible appearance	MIL-STD-202 Method 101
Thermal Shock	100 cycles between -65°C /+125°C 60 minutes at each extreme zone	|ΔR|: <10% No mechanical damage	MIL-STD-202 Method 107

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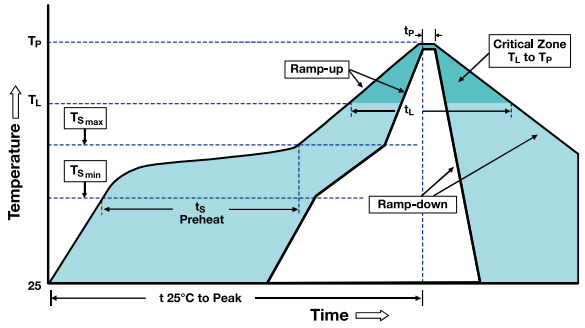
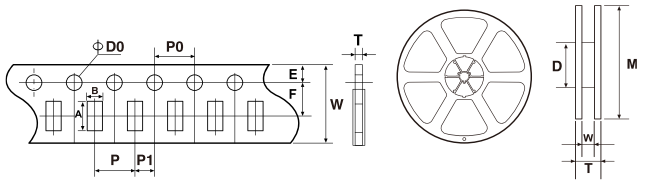
Soldering Parameters



Average Ramp-Up Rate (Ts_{max} to T_P)	3°C/second max.
Preheat	
-Temperature Min (Ts_{min})	150°C
-Temperature Max (Ts_{max})	200°C
-Time (Ts_{min} to Ts_{max})	60-120 seconds
Time maintained above:	
-Temperature (T_L)	217°C
-Time (t_L)	60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20 seconds
Ramp-Down Rate	6°C /second max.
Time 25°C to Peak Temperature	8 minutes max.

Note 1: All temperature refer to topside of the package, measured on the package body surface.
Note 2: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

Tape & Reel Specification (mm.)



A	3.50 ± 0.20
B	1.90 ± 0.20
W	8.00 ± 0.20
F	3.50 ± 0.05
E	1.75 ± 0.10
P	4.00 ± 0.10
P0	4.00 ± 0.10
P1	2.00 ± 0.10
D0	Ø 1.50 ± 0.10
T	0.75 ± 0.10

M	Ø 178.0 ± 2.0
W	9.5 ± 1.0
T	12.5 ± 1.5
A	2.0 ± 0.5
B	Ø 13.0 ± 0.5
C	Ø 21.0 ± 0.5
D	Ø 58.0 ± 2.0

Packaging Quantity

Part Number	Tape & Reel Quantity
SMFD1206PXXX	5000

Storage

- The ambient temperature recommended for storage shall be between 5°C ~30°C.
- The relative humidity recommended for storage shall be between 25%RH~60%RH.
- The products shall not be stored in areas where harmful gases containing sulfur or chlorine are present.

Warning

- Fuse product is not recommended for any type of coating. Polytronics is not responsible for any damage directly or indirectly related to the coating.
- For copper layer thickness or copper trace width different from the standard test board, fusing characteristics needs to be verified to ensure product performance meet user requirement.